

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KyuWon Lee	11/19/2010
HyunSu Shin	11/19/2010
Hun Jeong	11/19/2010
JinGwan Kim	11/19/2010
SunYoung Chun	11/19/2010
RECEIVING PARTY DATA	
Name:	STATS ChipPAC, Ltd.
Street Address:	10 Ang Mo Kio Street 65
Internal Address:	#05-17/20 Techpoint
City:	Singapore
State/Country:	SINGAPORE
Postal Code:	569059
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12951399
CORRESPONDENCE DATA	
Fax Number:	(602)748-4414
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	602-748-4408
Email:	main@plgaz.com
Correspondent Name:	Robert D. Atkins
Address Line 1:	605 W. Knox Road
Address Line 2:	Suite 104
Address Line 4:	Tempe, ARIZONA 85284
ATTORNEY DOCKET NUMBER:	2515.0312

OP \$40.00 12951399

501357570

**PATENT
 REEL: 025391 FRAME: 0243**

NAME OF SUBMITTER:

Robert D. Atkins

Total Attachments: 5

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ASSIGNMENT AND AGREEMENT


For good and valuable consideration, the receipt of which is hereby acknowledged, I, KYUWON LEE of Korea, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING PARTIALLY-ETCHED CONDUCTIVE LAYER RECESSED WITHIN SUBSTRATE FOR BONDING TO SEMICONDUCTOR DIE, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0312, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.



Signature for KYUWON LEE

Witnessed on this date: Nov 14th 2010

Signature of Witness: 

Printed Name of Witness: JIHOON OH

Address of Witness: 222-304 Dangrang, Paragori, Inje-Dang, Paldal - Gu, Suwon City, South Korea.

ASSIGNMENT AND AGREEMENT

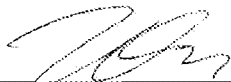
For good and valuable consideration, the receipt of which is hereby acknowledged, I, HYUNSU SHIN of Korea, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING PARTIALLY-ETCHED CONDUCTIVE LAYER RECESSED WITHIN SUBSTRATE FOR BONDING TO SEMICONDUCTOR DIE, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0312, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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Signature for HYUNSU SHIN

Witnessed on this date: November 19 '16

Signature of Witness: 

Printed Name of Witness: YoungDeuk Lee

Address of Witness: Samsil 1116 apt 121-1402, Samsil 2-dong
Gong-pa gu, Seoul, Korea

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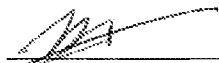
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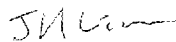


Signature for HUN JEONG

Witnessed on this date:

NOV. 19. 2010

Signature of Witness:



Printed Name of Witness:

Jaehyun Lim

Address of Witness:

646-10, Shillim 3 dong
Kwanak gu, Seoul, Korea

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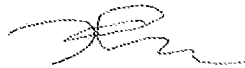
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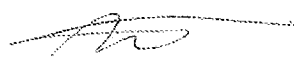
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Signature for JINGWAN KIM

Witnessed on this date: Nov 19th '16

Signature of Witness: 

Printed Name of Witness: Song, Hyan-Jin

Address of Witness: San 136-1 Ami-ri, Bubal-eub
Icheon-si Gyeonggi-do, 469-701

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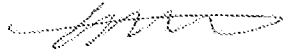
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Signature for SUNYOUNG CHUN

Witnessed on this date: November 19 '10

Signature of Witness: A

Printed Name of Witness: Song, Hyun-Jin

Address of Witness: 3-503 Chang-Won, Hynix semiconductor
Bubal eub, I-Cheun Si, Kyung-ki Do.